

| Ref # | Hits  | Search Query   | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|-------|--|---|------------------|---------|------------------|
| S3    | 1     | ("20050061496").PN.  | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/26 10:00 |
| S4    | 1     | ("6856016").PN.  | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/20 15:24 |
| S5    | 12973 | ((257/706,774,703,E51.04) or (438/122,125,629,637,639,640,667,668,672,675,700,701,713,978)). CCLS. or ("977").CLAS.            | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/28 15:45 |
| S6    | 1644  | ("977").CLAS.  | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/20 15:34 |
| S11   | 12973 | ((257/706,774,703,E51.04) or (438/122,125,629,637,639,640,667,668,672,675,700,701,713,978)). CCLS. or ("977").CLAS.            | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/21 12:32 |
| S15   | 13    | S11 and (carbon adj (nano\$tube nano adj tube)) and (die IC chip integrated adj circuit) and (heat adj sink heat adj spreader) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>IBM_TDB | OR               | ON      | 2005/10/21 17:48 |
| S16   | 21    | S11 and (organic adj (compound moiety)) and (thiol amide) and (die IC integrated adj circuit chip)                             | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>IBM_TDB | OR               | ON      | 2005/10/21 17:50 |
| S17   | 1     | ("6856016").PN.  | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/25 11:12 |
| S18   | 12990 | ((257/706,774,703,E51.04) or (438/122,125,629,637,639,640,667,668,672,675,700,701,713,978)). CCLS. or ("977").CLAS.            | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/25 15:35 |
| S27   | 5708  | (257/774,778,702,700).CCLS.  | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/26 10:53 |
| S31   | 425   | S27 and (heat adj sink heat adj spreader) and (gold Au) and (die IC chip integrated adj circuit) "2002. AY"                    | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>IBM_TDB | OR               | ON      | 2005/10/26 16:24 |
| S32   | 5708  | (257/774,778,702,700).CCLS.  | US-PGPUB;<br>USPAT;<br>USOCR                          | OR               | OFF     | 2005/10/26 16:30 |

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|-----|----|---|---|----|----|------------------|
| S33 | 17 | S32 and (heat adj sink heat adj spreader) and (DRAM dynamic adj random adj access adj memory) and (die IC chip integrated adj circuit) and (micro\$processor micro\$controller) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>IBM_TDB | OR | ON | 2005/10/26 16:31 |
|-----|----|---|---|----|----|------------------|